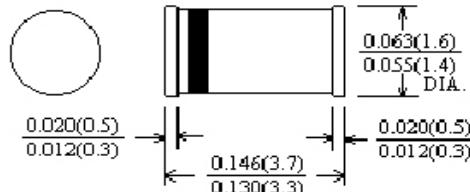


1N4150 mini-M.E.L.F. SIGNAL DIODE

MINI MELF (LL-34)

Mechanical Data

Items	Material
Package	mini MELF
Case	Hermetically sealed glass
Lead/Finish	Double stud/Tin Plating
Chip	Glass Passivated



Hermetically Sealed, Glass Silicon Diodes

Absolute Maximum Ratings (Ta=25 °C)

	Symbol	Value	UNIT
Reverse Voltage (continuous)	V _R	50	V
Power Dissipation at Tamb= 25 °C 3.33mW/ °C	P _{tot}	500	mW
Forward Current (DC)	I _F	300	mA
Average Rectified Output Current	I _O	200	mA
Repetitive Peak Forward Current	I _{FRM}	600	mA
Junction Temperature	T _j	-65 to +200	°C
Storage Temperature Range	T _s	-65 to +200	°C

Electrical Characteristics (Ta=25 °C)

	Symbol	Min	Max	Unit
Minimum Breakdown Voltage @I _R = 100uA	BV	75	-	V
Peak Forward Surge Current PW<1 sec	I _{Fsurge}	-	500	mA
Maximum Forward Voltage IF = 200 mA	V _F	-	1.0	V
Maximum reverse Leakage Current at VR = 50V at V _R = 50V, T _j = 150 °C	I _R	-	0.100 100	uA
Maximum Junction Capacitance V _R = 0, f= 1MHz	C _j	-	2.5	pF
Reverse Recovery Time I _F =10mA to 200mA, I _R =10mA to 200mA R _L =100 ohms Measured @ I _R = 0.1xI _F	trr	-	4	ns
Forward Recovery Time Measured from I=0 to I _F =200mA t _r =0.4ns, t _p =100ns, Duty Cycle ≤ 1.0% Measured @ V _F =1V	tfr	-	10	ns
Maximum Thermal Resistance Junction to Ambient Air	R _{thJA}	-	0.35	°C/mW